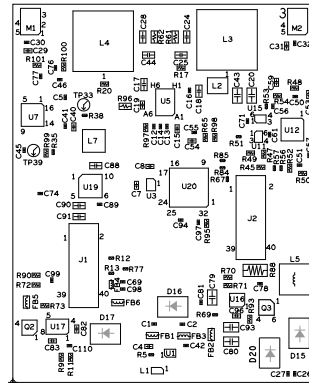
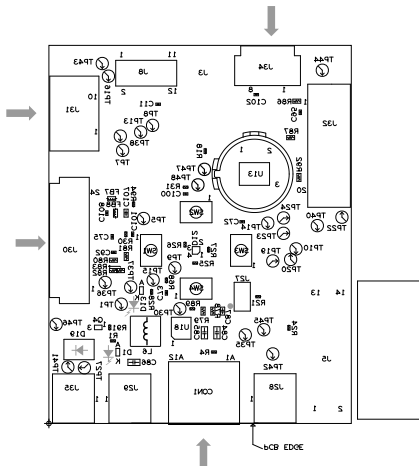


NOTE:

- 1.RECOMMENDED STENCIL THICKNESS - 4MIL
- 2.MARK APPROPRIATE DASH, REV. AND SERIAL NO. CHARACTERS TO BE PERMANENT AND LEGIBLE.
- 3.WORKMANSHIP OF ELECTRONIC ASSEMBLIES SHALL CONFORM TO IPC-A-610, CLASS 2.
- 4.ASSEMBLY IS STATIC SENSITIVE ALL PROCESS/HANDLING OPERATIONS MUST CONFORM TO E.S.D. PRACTICES CONTAINED WITHIN IPC-A-610.
- 5.MIC Handling and Storage Notes:(Read Page No. 31 to 35 of AN24 Sisonic Design Guide v1 for more assembly information)
Do not pull a vacuum over port hole of the microphone. Pulling a vacuum over the port hole can damage the device.
Do not board wash after the reflow process. Board washing and cleaning agents can damage the device.
Do not expose to ultrasonic processing or cleaning.
Do not brush board after the reflow process. Brushing the board with/without solvents can damage the device.
Do not insert any object in port hole of device at any time as this can damage the device.





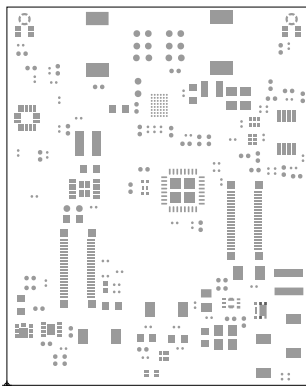
NXP SEMICONDUCTORS

DATE: 17JULY,2019

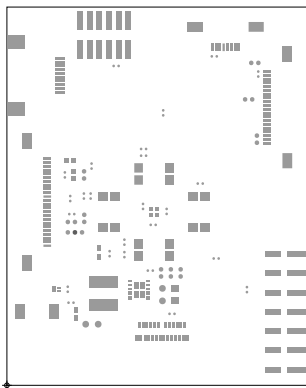
Rev:C

PART NO/CARD REF: RT Vision Board

FILM LAYER:ASB_ASSEMBLY BOTTOM



NXP SEMICONDUCTORS	
DATE: 17JULY,2019	
Rev:C	
PART NO/CARD REF: RT Vision Board	
FILM LAYER:SPT_SOLDER PASTE TOP	



NXP SEMICONDUCTORS	
DATE: 17JULY,2019	
Rev:C	
PART NO/CARD REF: RT Vision Board	
FILM LAYER:SPB_SOLDER PASTE BOTTOM	